

CLAIMS

I claim:

1. A test probe comprising:

one or more contact devices that are designed to provide a contact point for establishing
5 an electrical contact between each contact device of the one or more contact devices and a
device-under-test,

wherein

each contact device includes a bonding wire that is bonded to a first point and a second
point on the test probe, and

10 the contact point of each contact device is located on the bonding wire that forms the
contact device, between the first point and the second point.

2. The test probe of claim 1, wherein

the first point and the second point on the test probe of each contact device are
substantially adjacent.

3. The test probe of claim 2, wherein

the test probe includes one or more bond pads, and

the first point and the second point of each contact device on the test probe are located on
a common bond pad of the one or more bond pads.

4. The test probe of claim 3, wherein

the test probe includes an integrated circuit substrate, and

the one or more contact devices are located on the integrated circuit substrate.

5. The test probe of claim 4, wherein

the test probe includes one or more test circuits that are operably coupled to the one or
more contact devices.

6. The test probe of claim 5, wherein
at least one of the one or more test circuits is located on the integrated circuit substrate.

7. The test probe of claim 1, wherein

5 the test probe includes one or more bond pads, and
the first point and the second point of each contact device on the test probe are located on
a common bond pad of the one or more bond pads.

8. The test probe of claim 1, wherein

10 the test probe includes an integrated circuit substrate, and
the one or more contact devices are located on the integrated circuit substrate.

9. The test probe of claim 8, wherein

the test probe includes one or more test circuits that are operably coupled to the one or
more contact devices.

10. The test probe of claim 9, wherein

at least one of the one or more test circuits is located on the integrated circuit substrate.

11. The test probe of claim 1, wherein

the bonding wire includes a resilient material.

